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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 7353**  
Tetsuji TOGAWA et al. : Attorney Docket No. 2005\_1890A  
Serial No. 10/559,135 : Group Art Unit 3723  
Filed February 11, 2008 : Examiner Eileen P. Morgan

SUBSTRATE POLISHING APPARATUS  
AND SUBSTRATE POLISHING METHOD

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**RESPONSE**

THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

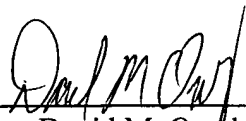
Sir:

Pursuant to the requirement contained in the Office Action mailed September 22, 2008, Applicants hereby elect invention I, claims 1-14, drawn to a method and apparatus for polishing a substrate.

In view of this election, a full examination on the merits of the present application is respectfully requested.

Respectfully submitted,

Tetsuji TOGAWA et al.

By:   
David M. Ovedovitz  
Registration No. 45,336  
Attorney for Applicants

DMO/jmj  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
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